



## DESCRIPTION

The ABS201~ABS210 are available in ABS package.

## FEATURES

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000V
- Forward Current - 2A
- High Surge Current Capability
- Designed for Surface Mount Application
- Available in ABS package

## ORDERING INFORMATION

Package Type	Part Number
ABS	ABS201
	ABS202
	ABS204
	ABS206
	ABS208
	ABS210
Note	SPQ: 5,000pcs/Reel
AiT provides all RoHS Compliant Products	

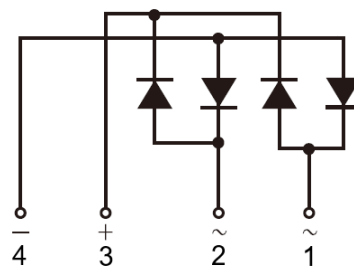
## MECHANICAL DATA

Case: ABS

Terminals: Solderable per MIL-STD-750,  
Method 2026

Approx. Weight: 88mg 0.0031oz

## PIN DESCRIPTION



1. Input Pin (~)
2. Input Pin (~)
3. Output Anode (+)
4. Output Cathode (-)



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbol	ABS201	ABS202	ABS204	ABS206	ABS208	ABS210	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_L=100^\circ\text{C}$	$I_o$	2.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	50						A
Forward Voltage Per Element	$I_F=2.0\text{A}$ $V_F$	1.0						V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$ $I_R$	5.0 100						$\mu\text{A}$
Typical Junction Capacitance <sup>NOTE1</sup>	$C_j$	25						pF
Typical Thermal Resistance <sup>NOTE2</sup>	$R_{\theta JA}$	65						$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 ~ 150						$^\circ\text{C}$

NOTE1: Measured at 1MHz and applied reverse voltage of 4V D.C.

NOTE2: Mounted on glass epoxy PC board with 4x(5x5mm<sup>2</sup>) copper pad.



## TYPICAL CHARACTERISTICS

Figure 1. Average Rectified Output Current

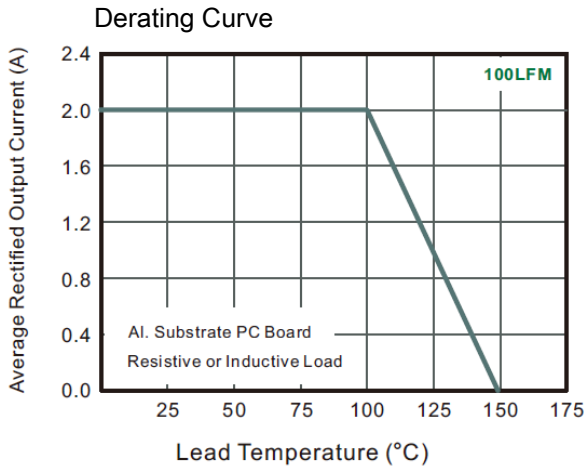


Figure 2. Typical Reverse Characteristics

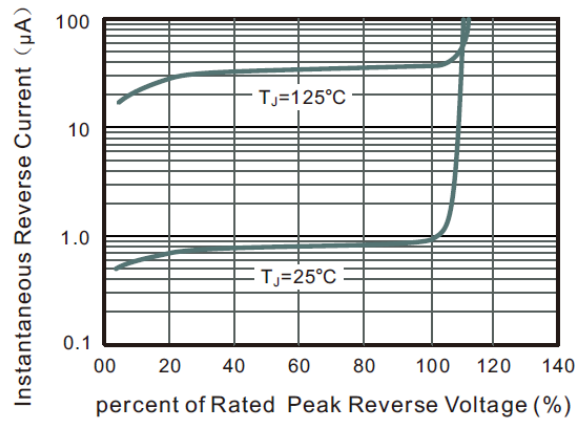


Figure 3. Typical Instantaneous Forward Characteristics

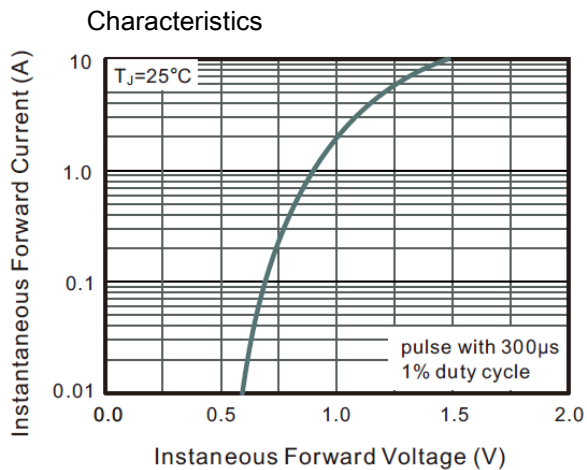


Figure 4. Typical Junction Capacitance

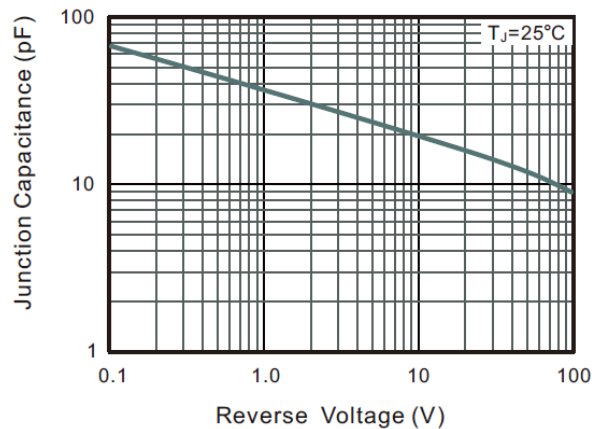
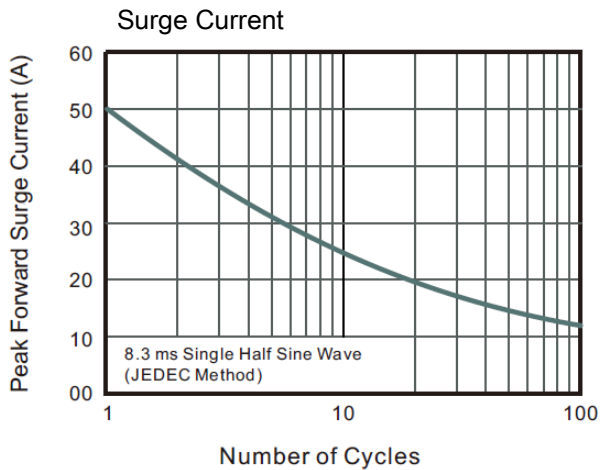


Figure 5. Maximum Non-Repetitive Peak Forward Surge Current

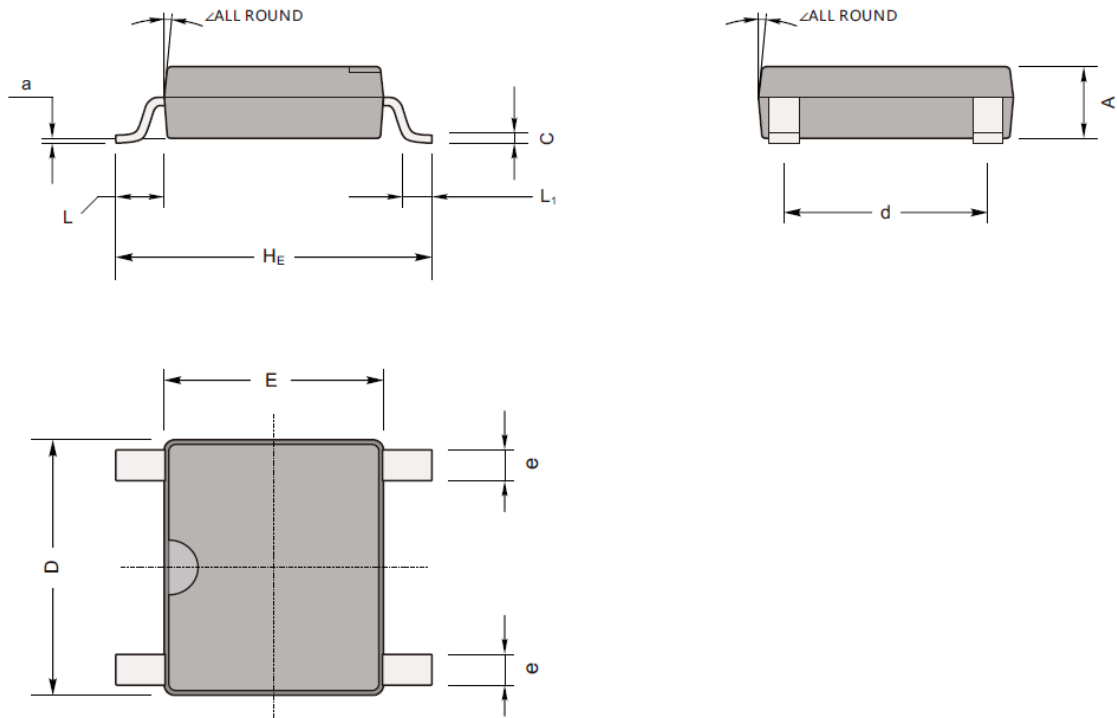




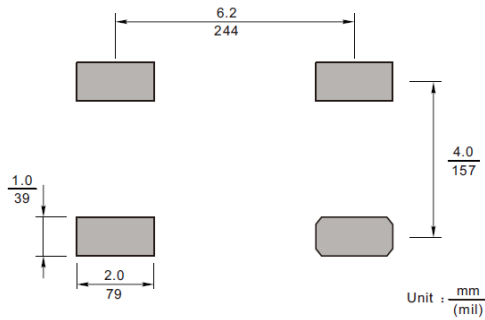
**PACKAGE INFORMATION**

Dimension in ABS Package (Unit: mm/mil)

Plastic surface mounted package; 4 leads



The recommended mounting pad size



UNIT		A	C	D	E	HE	d	e	L	L1	a	∠
mm	Min	1.3	0.15	4.9	4.2	6.0	3.8	0.5	0.95	0.6	0.2	7°
	Max	1.5	0.22	5.2	4.5	6.4	4.2	0.7				
mil	Min	51	5.9	193	166	236	150	20	37	24	4	
	Max	59	8.7	205	177	252	165	28				



## IMPORTANT NOTICE

AiT Semiconductor Inc. (AiT) reserves the right to make changes to any its product, specifications, to discontinue any integrated circuit product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

AiT Semiconductor Inc.'s integrated circuit products are not designed, intended, authorized, or warranted to be suitable for use in life support applications, devices or systems or other critical applications. Use of AiT products in such applications is understood to be fully at the risk of the customer. As used herein may involve potential risks of death, personal injury, or server property, or environmental damage. In order to minimize risks associated with the customer's applications, the customer should provide adequate design and operating safeguards.

AiT Semiconductor Inc. assumes to no liability to customer product design or application support. AiT warrants the performance of its products of the specifications applicable at the time of sale.